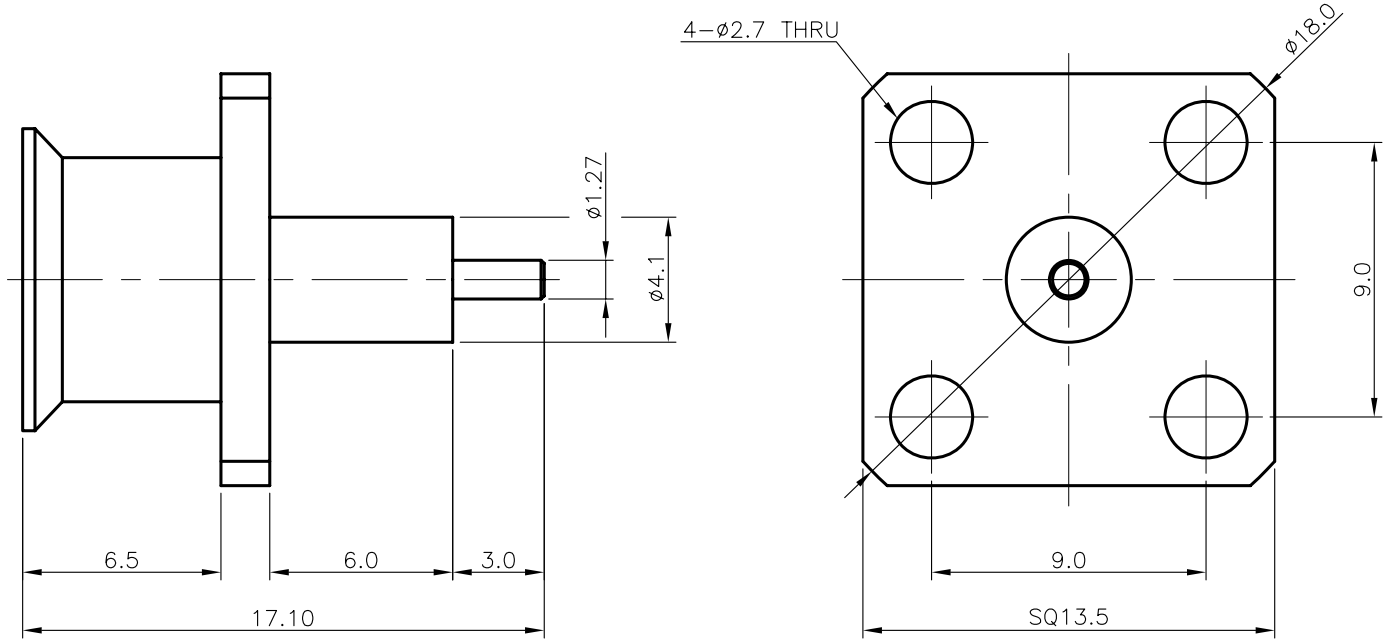
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2018.11.07.
1	BMBC 공용화 치수 적용	S.Y.EUN	I.C.KIM	2018.11.27.
2	완제품 치수 변경	S.Y.EUN	I.C.KIM	2020.02.04.



	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
	3	INSULATOR	1	TEFLON		DIN03008-N/2
1	2	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT03968-5/3
1	1	BODY	1	MBsBD C3604BD-F	Nickel Plate	DBD04430-5/2

TOLERANCE	Decimal ±0.1	DATE	2018. 11. 27.
	Angle ±1°	APPROVED BY	I.C.KIM
		CHECKED BY	
MATERIAL		DRAWN BY	S.Y.EUN
FINISH		SCALE 4/1	UNIT mm

KJ COMTECH
KJ COMTECH CO.,LTD.
RF & MICROWAVE TECHNOLOGY
Tel : 82-32-347-8015
Fax : 82-32-347-8017

TITLE
BMBC50 SOLDER END JS-4H

A4

DWG NO. CN03910-7/2

REVISION 2

SHEET 1 of 1